

# **Customer Information Notification**

Issue Date: 10-Aug-2016 Effective Date: 10-Sep-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

# 201607015I



# **Management Summary**

Update of data sheets

Chang	e Cate	gorv

[] Wafer Fab	[] Assembly	[] Product Marking	[] Test	[] Design
Process	Process		Location	
[] Wafer Fab	[] Assembly	[] Mechanical Specifica	tion []Test Proc	ess [] Errata

Materials

[] Wafer Fab

[] Assembly
Location

Materials

[] Test

[X] Electrical spec./Test
Equipment

Equipment

Coverage

Data sheet update of PESD12VV1BL & PESD36VS1UL

# **Information Notification**

Removal of incorrect packing information in data sheets.

Correct packing information for products in SOD882 package is separately provided via NXP website (http://www.nxp.com/documents/packing/SOD882 315.pdf).

## Why do we issue this Information Notification

Update of data sheets

#### **Identification of Affected Products**

Product identification does not change

## **Impact**

No impact on form, fit or function of the products.

## **Data Sheet Revision**

A new datasheet will be issued

## **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

#### **About NXP Semiconductors**

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#### **Affected Part Numbers**

PESD36VS1UL,315 PESD12VV1BL,315 PESD12VV1BL,315 PESD36VS1UL,315